

P6KE100CA, P6KE10A, P6KE10CA, P6KE110A, P6KE110A, P6KE110CA, P6KE11A, P6KE11CA, P6KE120A, P6KE120CA, P6KE12A, P6KE12CA, P6KE12CA, P6KE130A, P6KE130CA, P6K P6KE13CA, P6KE150A, P6KE150CA, P6KE15A, P6KE15CA, P6KE16CA, P6KE160CA, P6KE16CA, P6KE16CA, P6KE170CA, P6KE170CA, P6KE180CA, P6KE180CA, P6KE18CA, P6KE20CA, P P6KE27CA, P6KE300A, P6KE300A, P6KE30A, P6KE30A, P6KE30A, P6KE33A, P6KE33CA, P6KE350A, P6KE350A, P6KE36A, P6KE36A, P6KE39A, P6KE39A, P6KE39A, P6KE30A, P6KE30 P6KE400CA, P6KE43CA, P6KE43CA, P6KE47CA, P6KE51CA, P6KE51CA, P6KE56CA, P6KE56CA, P6KE62CA, P6KE62CA, P6KE68CA, P6KE6 P6KE6V8CA, P6KE75CA, P6KE75CA, P6KE7V5A, P6KE7V5CA, P6KE8V2CA, P6KE8V2CA, P6KE8V2CA, P6KE9V1A, P6KE9V1CA, P6KE

P6KExxx(C)A-13

Weight (mg): 400

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)		Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Si	7440-21-3	96.52%	0.29	1.15	965200	2775
		PbO	1317-36-8	2.52%			25200	72
		Ni	7440-02-0	0.96%			9600	28
Solder Paste	RoHS Exempt	Pb(92.5%)	7439-92-1	92.50%	1.20	4.8	925000	11100
	High	Sn(5%)	7440-31-5	5.00%			50000	600
	Temperature	Ag(2.5%)	7440-22-4	2.50%			25000	300
Axial Lead	Copper Alloy	Cu	7440-50-8	99.99%	70.50	282	999922	704945
		Ag	7440-22-4	0.00%			24	17
		Zn	7440-66-6	0.00%			20	14
		S	7704-34-9	0.00%			14	10
		P	7723-14-0	0.00%			10	7
		Fe	7439-89-6	0.00%			10	7
Encapsulation		Silica (SiO2) (60~80%)	14808-60-7	70.00%	27.01	108.05	700000	189088
		Polymer with 1-chloro-2,3-epoxypropane and formaldehyde (10~20%)	29690-82-2	15.00%			150000	40519
		Phenol-formaldehyde polymer (5~15%)	9003-35-4	10.00%			100000	27013
		Sb2O3 (0~5%)	1309-64-4	2.50%			25000	6753
		TBBA-diglycidyl-ether oligomer (0~5%)	40039-93-8	2.50%			25000	6753
Lead Plating Finish	Tin Solder	Sn (>99.5%)	7440-31-5	100.00%	1.00	4	1000000	10000
· · · · · · · · · · · · · · · · · · ·				Total	100.00	400.00		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

This product or product family does not contain any of the following substances except as CURRENTLY exempted by ELV II and RoHS and reported above:

Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)

Ozone Depleting Substances - Class II (HCFCs) Azo compounds Perfluorooctane Sulphonate (PFOS) or related compounds

Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) includin**DecaBDE** Cadmium and cadmium compounds Certain Shortchain Chlorinated Paraffins Polychlorinated Biphenyls (PCBs)

Chlorinated organic compounds Polychlorinated Naphthalenes (> 3 chlorine atoms)

Hexavalent chromium compounds Radioactive Substances

Lead and lead compounds Tributyl Tin (TBT) and Triphenyl Tin (TPT)

Mercury and mercury compounds Tributyl Tin Oxide (TBTO) Organic tin compounds

This product or product family meet REACH requirements for chemicals designated by the European Chemicals Agency (ECHA) as Substances of Very High Concern (SVHC) appended below:

Bis (2-ethyl(hexyl)phthalate) (DEHP) Hexabromocyclododecane (HBCDD) Bis(tributyltin)oxide (TBTO) 4,4'- Diaminodiphenylmethane Dibutyl phthalate (DBP) Cyclododecane Lead hydrogen arsenate Triethyl arsenate Cobalt dichloride Benzyl butyl phthalate (BBP) Diarsenic pentaoxide

Diarsenic trioxide

5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Alkanes, C10-13, chloro (SCCPs - Short Chain Chlorinated Paraffins) Sodium dichromate, dihydrate

RoHS Exemptions 5 for Pb in glass and 7a for Pb in High Temperature, High %Pb in Solder are applied.

^{*} The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products.